



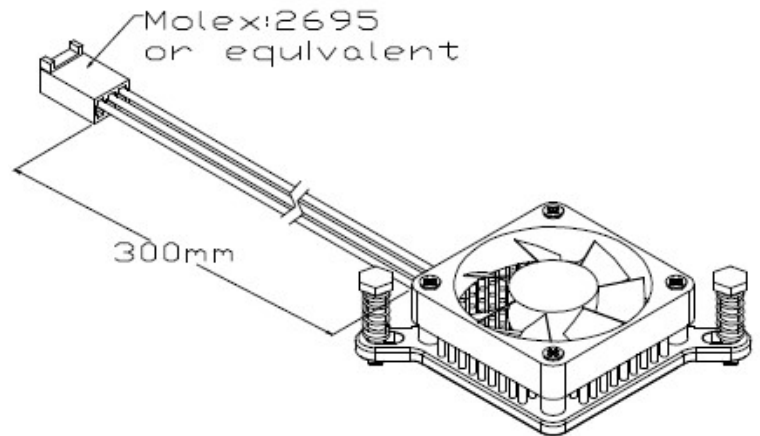
# Model : MBF37.5006-17P/CU/2.6

## BGA Heat Sink Specification

For 37.5x37.5 Chip set



1. Material : CU1100
2. Dimension :  
Foot print : 37.5x37.5mm  
Height : 17 mm  
Base (thickness) : 2.6mm
3. Finish: Passivation
4. Accessory :  
Push pin & spring: Nylon-66 & SWP-B  
Fit for PCB Ø3.1-3.2  
Fan spec: 50LFM



## Performance

Heat Source (LxW)	37.5x37.5
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